

N-Channel Enhancement Mode Power MOSFET

General Description

The TF3622DS is the highest performance trench N-ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charges for most of the synchronous buck converter applications.

The TF3622DS meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Application

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

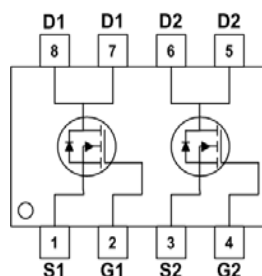
Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

Product Summary

BVDSS	RDSON(typ)	ID
30V	10 mΩ (V _{GS} =10V)	12A

SOP- 8



Schematic diagram



Y :year code W :week code

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	30	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	12	A
I _D @T _C =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	7.5	A
I _{DM}	Pulsed Drain Current ²	40	A
EAS	Single Pulse Avalanche Energy ³	20	mJ
I _{AS}	Avalanche Current	10	A
P _D @T _A =25°C	Total Power Dissipation ⁴	15	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-ambient ¹	---	40	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	7.0	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, (unless otherwise noted))

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V$, $I_D=250\mu A$	30	---	---	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance ²	$V_{GS}=10V$, $I_D=10A$	---	10	13	$m\Omega$
		$V_{GS}=4.5V$, $I_D=8A$	---	15	18	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250\mu A$	1.0	1.2	2.1	V
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=28V$, $V_{GS}=0V$, $T_J=25^\circ\text{C}$	---	---	1	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V$, $V_{DS}=0V$	---	---	± 100	nA
gfs	Forward Transconductance	$V_{DS}=5V$, $I_D=10A$	10	---	---	S
R_g	Gate Resistance	$V_{DS}=0V$, $V_{GS}=0V$, $f=1\text{MHz}$	---	3.6	---	Ω
Q_g	Total Gate Charge (4.5V)	$V_{DS}=30V$, $I_D=10A$, $V_{GS}=10V$	---	19.5	---	nC
Q_{gs}	Gate-Source Charge		---	2.45	---	
Q_{gd}	Gate-Drain Charge		---	3.9	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=30V$, $I_D=1.5A$ $V_{GS}=10V$, $R_{GEN}=1\Omega$	---	4.4	---	ns
T_r	Rise Time		---	9	---	
$T_{d(off)}$	Turn-Off Delay Time		---	17	---	
T_f	Fall Time		---	6	---	
C_{iss}	Input Capacitance	$V_{DS}=15V$, $V_{GS}=0V$, $f=1\text{MHz}$	---	1021	---	pF
C_{oss}	Output Capacitance		---	273	---	
C_{rss}	Reverse Transfer Capacitance		---	166	---	

Guaranteed Avalanche Characteristics

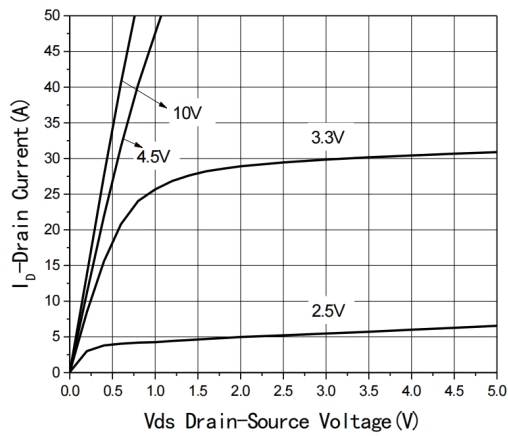
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
EAS	Single Pulse Avalanche Energy ⁵	$V_{DD}=25V$, $L=0.5\text{mH}$, $I_{AS}=9A$	16	---	---	mJ

Diode Characteristics

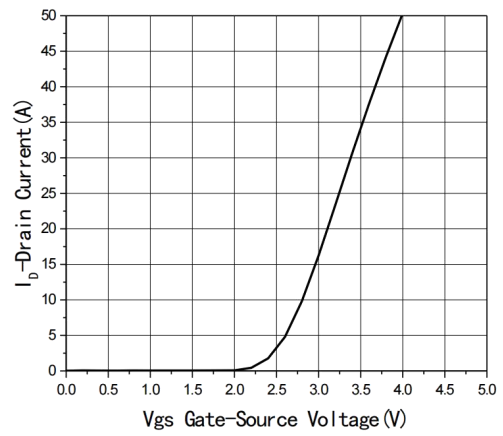
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current ^{1,6}	$V_G=V_D=0V$, Force Current	---	---	2	A
I_{SM}	Pulsed Source Current ^{2,6}		---	---	50	A
V_{SD}	Diode Forward Voltage ²	$V_{GS}=0V$, $I_S=10A$, $T_J=25^\circ\text{C}$	---	---	1.1	V
t_{rr}	Reverse Recovery Time	$I_F=10A$ $dI/dt=100A/\mu s$, $T_J=25^\circ\text{C}$	---	6	---	nS
Q_{rr}	Reverse Recovery Charge		---	3.9	---	nC

Note :

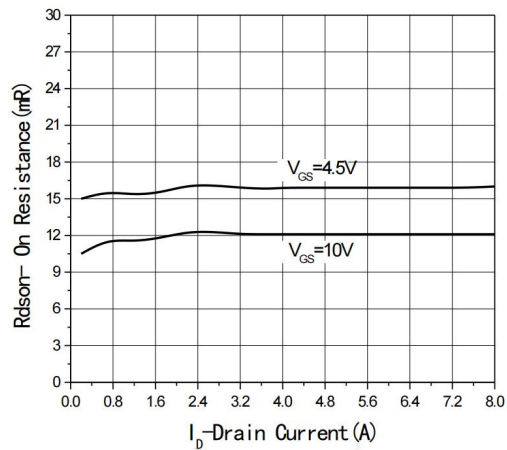
- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, $t<10\text{sec}$.
- 2.The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{DD}=25V$, $V_{GS}=10V$, $L=0.5\text{mH}$, $I_{AS}=9A$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The Min. value is 100% EAS tested guarantee.
- 6.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.



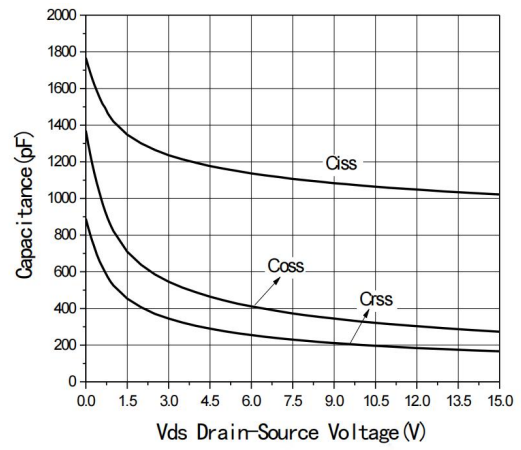
Output Characteristics



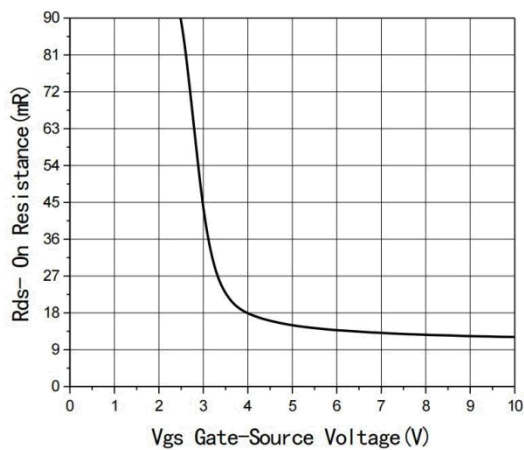
Typical Transfer Characteristics



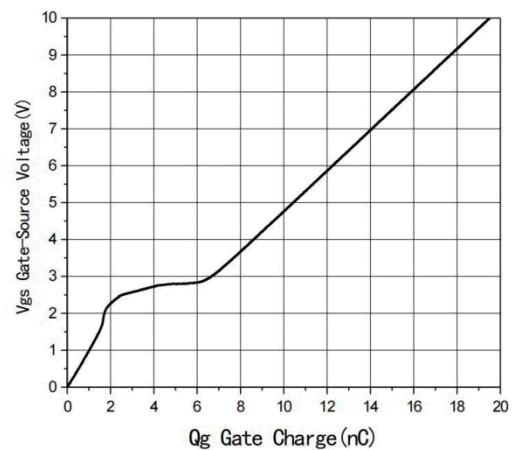
$R_{DS(on)}$ -Drain current



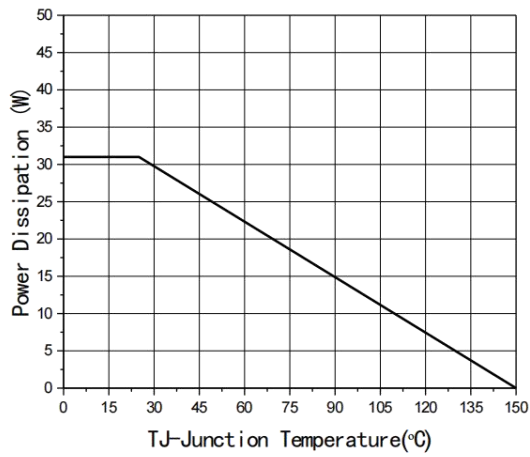
Capacitance vs V_{DS}



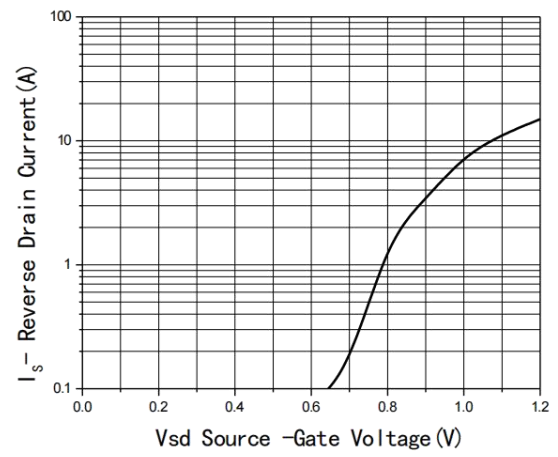
$R_{DS(on)}$ -Gate Drain voltage



Gate Charge

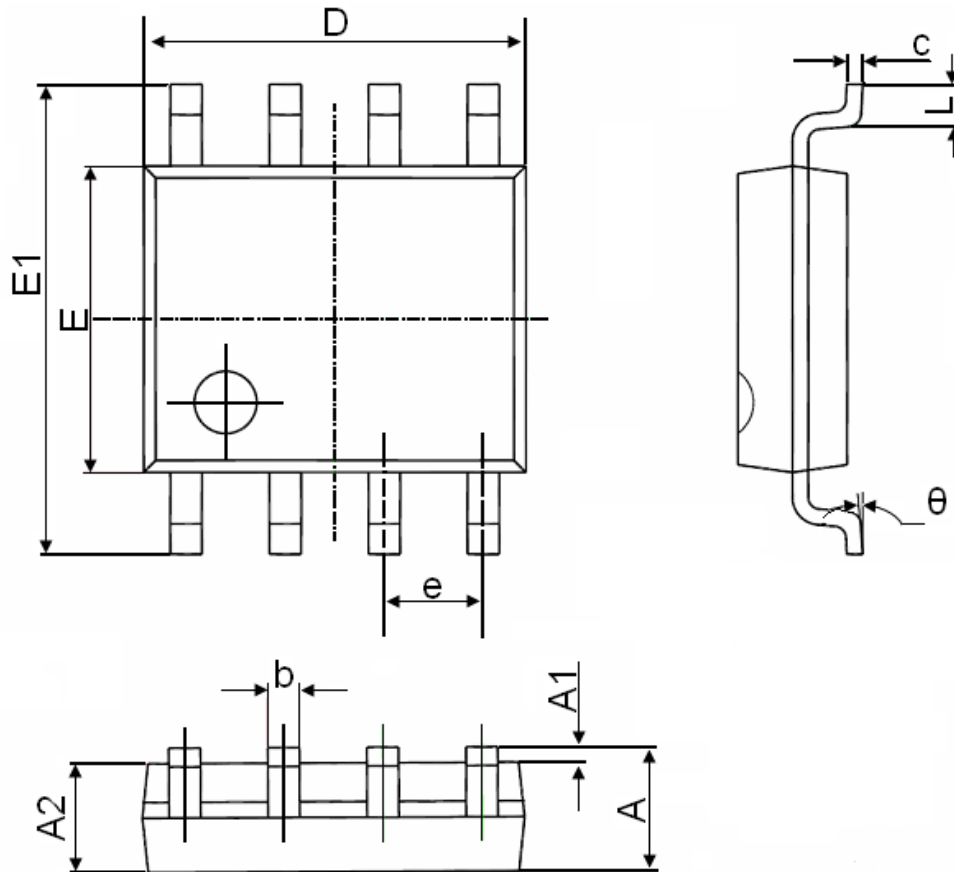


Power De-rating



Source-Drain Diode Forward

SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°